

Wave soldering flux with powerful wetting

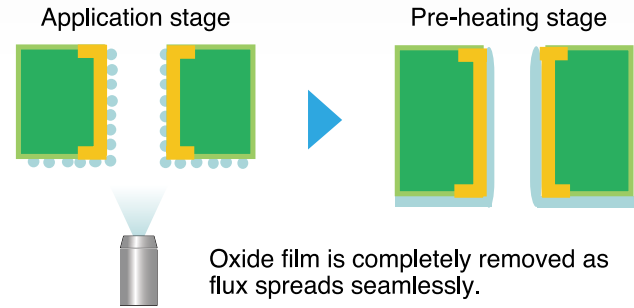
JS-E-15X

Ultimate “Uniform application quality” and “Powerful wetting”

Forms seamless flux layer

By having the optimal size of fine flux particles, JS-E-15X easily spreads uniformly over the whole surface and forms a seamless flux layer. Thus JS-E-15X completely removes the oxide film and also prevents any re-oxidization at the end of pre-heating.

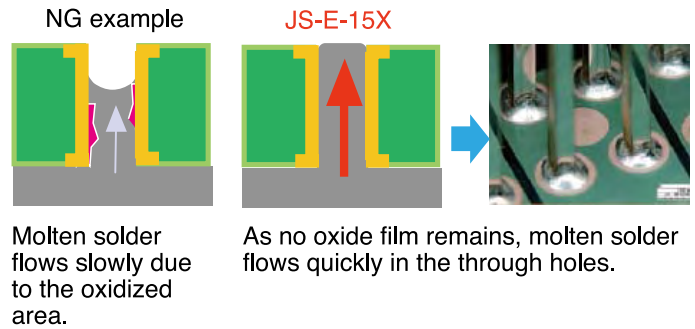
Figure 1. Flux behavior with JS-E-15X



Excellent through hole filling

JS-E-15X demonstrates quick and powerful wetting performance by the removal of the oxide film and prevention of re-oxidization during pre-heating. This combined with sufficient fluidity during soldering process ensures excellent hole filling.

Figure 2. Solder behavior in through hole filling



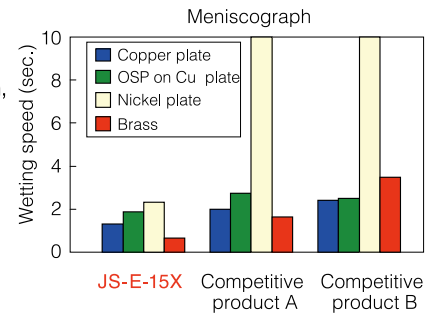
Compatible with various materials

JS-E-15X delivers sufficient wetting performance to severely oxidized materials such as nickel and brass, and is also applicable for selective soldering.

Figure 3. Meniscograph test

Test conditions

- Test piece Kept at 85°C85%RH x 24h, left 3h at room temp. afterwards
- Measurement conditions Instrument: SAT-5000 Application method: Dip (2mm) Pre-heating: None Solder bath temp.: 245°C (Pb free) Dip speed: 5 mm/sec. Dip time: 10 sec.



Product specifications	
Product name	JS-E-15X
Solid content (%)	14.8
Specific gravity (at 20°C)	0.822
Halide content (%)	0.089
Flux type	ROM1
Application	Spray / foam Wave soldering

- Excellent thru hole filling
- Powerful wetting
- Anti bridging
- Applicable for selective soldering
- Inhibits solder beading
- Applicable solder alloy: Sn/Ag/Cu type, Sn/Cu type
- No clean type
- No-clean**